



NC-559-ASM-TF, No-Clean Tacky Flux

Product Data Sheet

Product Highlights

- ROLO flux classification
- Wide process window
- Excellent wetting compatibility on most board finishes
- Clear residue
- High temperature compatible

Application

NC-559-ASM-TF is formulated for syringe, stencil printing, and rework applications on all PCB surface finishes.

NC-559-ASM-TF may be used for BGA sphere attachment and reballing. NC-559-ASM-TF is also designed to work on all flip chip bumping and chip scale packaging sites.

Compatible Alloys

Alloy	Temp °C	Temp °F
63Sn/37Pb	183	361
62Sn/36Pb/2Ag	179	354
62.8Sn/36.8Pb/0.4Ag	179-183	354-361
60Sn/40Pb	183-191	361-376
43Sn/43Pb/14Bi	144-163	291-325
42Sn/58Bi	138	280
10Sn/88Pb/2Ag	268-290	514-554

Test Results

Test J-STD-004 or other requirements (as stated)	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (no-clean)
Surface Insulation Resistance 85 °C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: 100 M (no-clean)
Viscosity - Malcom @ 10 RPM/25 °C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	40-52
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	May contain up to 7% w/w of ethoxylated 4-nonylphenol

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Cleaning

NC-559-ASM-TF is a no-clean tacky flux that can be left on the board for many SMT assemblies. For applications requiring cleaning, NC-559-ASM-TF can be cleaned using commercially available flux residue removers such as Kyzen Aquanox A4241, A4520, A4625 and A4625B (Batch Cleaners). Kyzen brand cleaners are available from Amtech.

Recommended Profile

This profile is designed to serve as a starting point for process optimization using NC-559-ASM-TF. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone, (140-180 °C) for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <60 seconds.

AMTECH Part Numbers

NC-559-ASM-TF, 75 gram jar: Part Number: 16099

NC-559-ASM-TF, 30cc syringe: Part Number: 16100

Other packaging available upon request.

Storage and Handling

Tacky flux should be stored at room temperature (20-25 °C). Syringes and cartridges should be stored vertically with the dispensing tip down. Properly stored tacky flux has a 12 month shelf life.

Packaging

10 & 30cc syringes

75 & 150 gram jars

170 & 340 gram cartridges

